

## DESCRIPTION

### INGOT CUTTING METHOD AND WIRE SAW

#### TECHNICAL FIELD

[0001]

The present invention relates to a method for slicing an ingot into a wafer shape by a wire saw and to a wire saw.

#### BACKGROUND ART

[0002]

In recent years, an increase in size of a wafer has been demanded, and a wire saw is mainly used for slicing an ingot with this increase in size.

The wire saw is a device that allows a wire (a high tensile steel wire) to travel at high speed, presses a workpiece (there is, e.g., a silicon ingot. It may be simply referred to as an ingot hereinafter) against the wire while apply slurry to the wire, and slices the workpiece to provide many wafers at the same time (see Patent Literature 1).

[0003]

Here, FIG. 4 shows an outline of an example of a conventional general wire saw.

As shown in FIG. 4, a wire saw 101 is mainly constituted of a wire 102 configured to slice an ingot, a wire guide 103 around which the wire 102 is wound, a tension imparting mechanism 104 configured to impart tension to the wire 102, ingot feeding means 105 for feeding the ingot to be sliced, a nozzle 106 configured to supply slurry provided by dispersing and mixing abrasive grains such as SiC fine powder in a coolant, and others.

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